Silicon Carbide Schottky Diode

1200 V, 10 A

Description

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size & cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 100 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery / No Forward Recovery
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

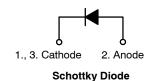
Applications

- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuits



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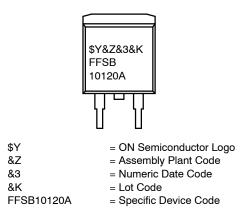
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D²PAK-3 (TO-263, 3-LEAD) CASE 418AJ

MARKING DIAGRAM



ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

Symbol	Parameter	Value	Unit	
V _{RRM}	Peak Repetitive Reverse Voltage		1200	V
E _{AS}	Single Pulse Avalanche Energy (Note 1)		100	mJ
١ _F	Continuous Rectified Forward Current @ T _C < 164°C		10	А
	Continuous Rectified Forward Current @ T_C <	21	1	
I _{F, Max}	Non-Repetitive Peak Forward Surge Current	T _C = 25°C, 10 μs	850	А
		T _C = 150°C, 10 μs	800	А
I _{F,SM}	Non-Repetitive Forward Surge Current	Half-Sine Pulse, t _p = 8.3 ms	90	А
I _{F,RM}	Repetitive Forward Surge Current Half-Sine Pulse, tp = 8.3 ms		35	А
Ptot	Power Dissipation	$T_{\rm C} = 25^{\circ}{\rm C}$	283	W
		T _C = 150°C	47	W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C
	TO-247 Mounting Torque, M3 Screw	60	Ncm	

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. E_{AS} of 100 mJ is based on starting $T_J = 25^{\circ}$ C, L = 0.5 mH, $I_{AS} = 20$ A, V = 50 V.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ extsf{ heta}JC}$	Thermal Resistance, Junction to Case, Max	0.53	°C/W

ELECTRICAL CHARACTERISTICS (T_C = 25° C unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V _F	Forward Voltage	I _F = 10 A, T _C = 25°C	-	1.45	1.75	V
		I _F = 10 A, T _C = 125°C	-	1.7	2.0	
		I _F = 10 A, T _C = 175°C	-	2.0	2.4	
I _R	Reverse Current	$V_{\rm R}$ = 1200 V, $T_{\rm C}$ = 25°C	-	-	200	μΑ
		V_{R} = 1200 V, T_{C} = 125°C	-	-	300	
		V_{R} = 1200 V, T_{C} = 175°C	-	-	400	
Q _C	Total Capacitive Charge	V = 800 V	-	62	-	nC
С	Total Capacitance	V _R = 1 V, f = 100 kHz	-	612	-	pF
		V _R = 400 V, f = 100 kHz	-	58	-	
		V _R = 800 V, f = 100 kHz	-	47	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Part Number	Top Marking	Package	Shipping
FFSB10120A	FFSB10120A	D ² PAK–3 (Pb-Free / Halogen Free)	800 / Tape & Reel

TYPICAL CHARACTERISTICS

(T_J = 25°C unless otherwise noted)

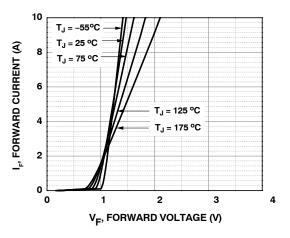


Figure 1. Forward Characteristics

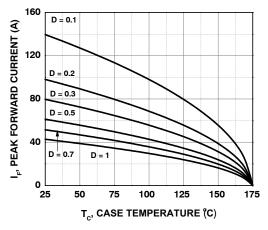


Figure 3. Current Derating

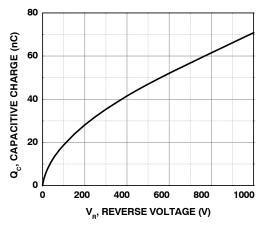


Figure 5. Capacitive Charge vs. Reverse Voltage

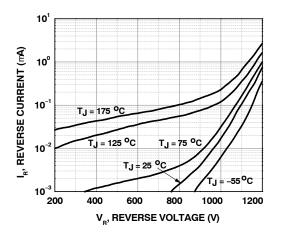


Figure 2. Reverse Characteristics

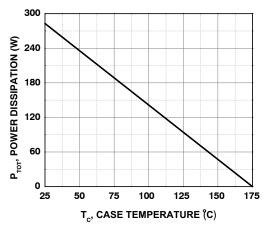
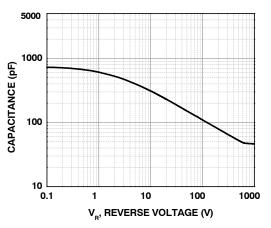
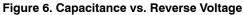


Figure 4. Power Derating





TYPICAL CHARACTERISTICS

(T_J = 25° C unless otherwise noted)

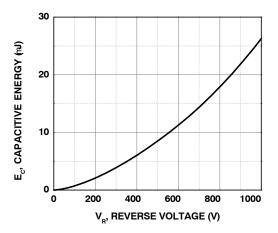


Figure 7. Capacitance Stored Energy

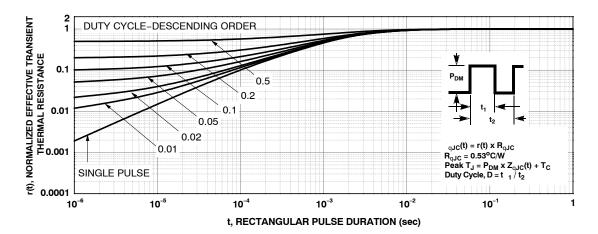


Figure 8. Junction-to-Case Transient Thermal Response Curve

TEST CIRCUIT AND WAVEFORMS

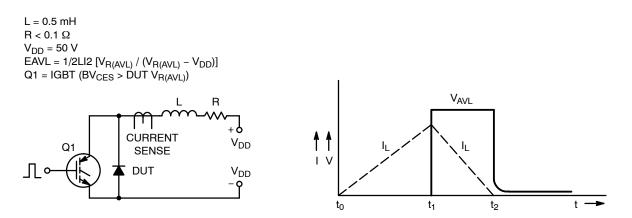
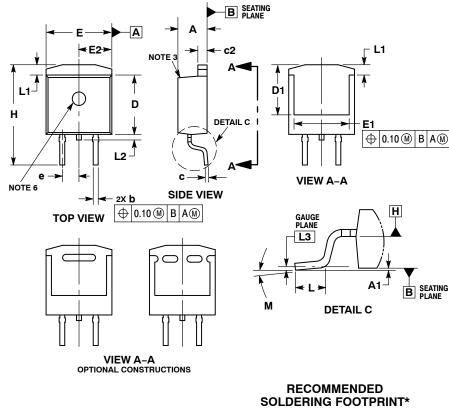


Figure 9. Unclamped Inductive Switching Test Circuit & Waveform

PACKAGE DIMENSIONS

D²PAK-3 (TO-263, 3-LEAD) CASE 418AJ **ISSUE B**

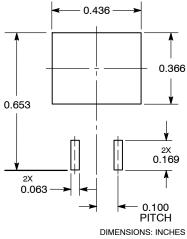


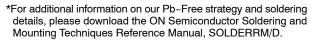
NOTES:

- NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: INCHES. 3. CHAMFER OPTIONAL 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.005 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLAS-TIC BODY AT DATUM H. 5. THERMAL PAD CONTOUR IS OPTIONAL WITHIN DIMENSIONS E, L1, D1 AND E1. 6. OPTIONAL MOLD FEATURE

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.160	0.190	4.06	4.83
A1	0.000	0.010	0.00	0.25
b	0.020	0.039	0.51	0.99
С	0.012	0.029	0.30	0.74
c2	0.045	0.065	1.14	1.65
D	0.330	0.380	8.38	9.65
D1	0.260		6.60	
Е	0.380	0.420	9.65	10.67
E1	0.245		6.22	
е	0.100 BSC		2.54 BSC	
н	0.575	0.625	14.60	15.88
L	0.070	0.110	1.78	2.79
L1		0.066		1.68
L2		0.070		1.78
L3	0.010 BSC		0.25 BSC	
М	0°	8°	0°	8°

SOLDERING FOOTPRINT*





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